IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
upplier Informa	tion														
Company name*			Company unique ID			τ	Unique ID Authority				Resp	Response Date*			
nsemi										2025	2025-05-08				
ontact Name			Title - Contact			I	Phone - Contact*				Ema	Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Pro	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			I	Phone - Representative*				Ema	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Pro	Product-Env-Stewards@onsemi.com			
Requester 1	Requester Item Number Mf		fr Item Number Mfr Item Name				Effective Date	Versio	n	Manufacturing Site		Weight*	UOM	Unit Type	
		1N5233BTR 6V 500MW 5% ZENE		ENER DO35		2025-05-08	CN2			109.66989	mg	Each			
	roccess Informatio											- lar .			
8					-STD-020 MS	L Rating		Peak Process Body Temperature Max Time		İ	1.		of Reflow Cy	cles	
	(Sn) - annealed	C	U Alloy	N	JA .		0		C	30	Se	econds 3			
omments															
r more information	regarding material cor	nposition p	olease refer to	page 3											

RoHS Material Composition Declaration			Declaration 7	Гуре *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and cornect to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s	does not contain RoHS restricted substances	per the definition above except for sele	ted exemptions	Supplier Acceptance	* Accepted						
Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	E									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
CSS Wire	75.0	mg	Supplier	Iron (Fe)	7439-89-6		63.75	mg
			Supplier	Copper (Cu)	7440-50-8		11.25	mg
Die	0.024358	mg	Supplier	Titanium (Ti)	7440-32-6		0	mg
			Supplier	Silver (Ag)	7440-22-4		0.0115	mg
			Supplier	Silicon (Si)	7440-21-3		0.0127	mg
			В	Nickel (Ni)	7440-02-0		0.0001	mg
Dumet Wire	8.5	mg	Supplier	Manganese (Mn)	7439-96-5		0.085	mg
			Supplier	Silicon (Si)	7440-21-3		0.0595	mg
			В	Nickel (Ni)	7440-02-0		2.6775	mg
			Supplier	Iron (Fe)	7439-89-6		3.6805	mg
			Supplier	Copper (Cu)	7440-50-8		1.9975	mg
Glass Encapsulation	23.5	mg	Supplier	Boron Trioxide (B2O3)	1303-86-2		0.705	mg
			A	Lead Oxide (PbO)	1317-36-8	7c	14.382	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.0118	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		0.8813	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		7.52	mg
Marking Ink	0.01953	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.004	mg
			Supplier	Formaldehyde, polymer with 4,4-(1-methylethylidene)bisphenol	25085-75-0		0.0052	mg
			Supplier	Proprietary	Proprietary Data		0.0009	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.001	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0013	mg
			Supplier	Diethylene glycol 2-ethyhexyl-ether	1559-36-0		0.0025	mg
			Supplier	Amino Resin	68002-20-0		0.0033	mg
			Supplier	2,2,4-Trimethyl-1,3-pentanediol di is Obutyrate	6846-50-0		0.0013	mg
Plating	2.626	mg	Supplier	Tin (Sn)	7440-31-5		2.626	mg